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To	t. 103656536
1.	Name of conveying party:
	1.) Zin O YOO
2.	Name and Address of receiving party:
	SAMSUNG ELECTRO-MECHANICS CO., LTD. 314 Maetan-3-dong, Yeongtong-gu, Suwon, Gyunggi-do, Republic of Korea
3.	Nature of conveyance:  X
4.	Application number(s) or patent number(s):  This document is being filed together with a new application.  OR
	<ul> <li>☐ This document is being filed after filing of the application:</li> <li>(a) Patent Application No(s). 13/827,497, filed March 14, 2013; or</li> <li>(b) Patent No(s).</li> </ul>
5.	Name and address of party to whom correspondence concerning document should be mailed: STAAS & HALSEY LLP Our Docket: 1938.1662 Attention: David M. Pitcher 1201 New York Ave., N.W., 7th Floor Washington, D.C. 20005
6.	Total number of applications and patents involved:1
7.	Total fee (37 CFR 3.41) (\$ 40.00 per Patent or Application in Assignment)  ☐ Enclosed ☐ Authorized to be charged to credit card. ☐ Authorized to be charged to deposit account.
8.	Deposit Account No.: 19-3935 (Any underpayment is authorized to be charged to this Deposit Account) (Attach duplicate copy of this page if paying by deposit account)
	id M. Pitcher, Reg. No. 25,908 ne of Person Signing  Signatule  101 FC:8021  Total number of pages including cover sheet: 2
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Revised April, 2011

Docket No.

## U.S. ASSIGNMENT

S&H 7/03

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by (Insert Name(s) & Address(es) of ASSIGNEE(S))

## SAMSUNG ELECTRO-MECHANICS CO., LTD. 314 Maetan-3-dong, Yeongtong-gu, Suwon, Gyunggi-do, Republic of Korea

(hereinafter, "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

## PACKAGE SUBSTRATE, MANUFACTURING METHOD THEREOF, AND MOLD THEREFOR

relating to International Patent Application PCT// executed on even date herewith or, if not so executed, was:	and/or for which application for Letters Patent of the United States was
(a) executed on;	(Insert date of execution of application, if not concurrent)
(b) filed on; Serial No;	Any registered attorney of STAAS & HALSEY LLP, 1201 New York Ave., N.W., Suite 700, Washington, D.C. 20005 (202/434-1500) is hereby authorized to insert in (b) the specified data, when known.
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IN WITNESS WHEREOF, the undersigned inventor(s) (Typed Name & Signature of Inventor(s)) (Date)	
1) YOO, ZINO MY 5th March	20/3

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